

CLAIMS

1. A thermosetting resin film for forming a first protective film on a surface having a bump of a semiconductor wafer by being attached to the surface and being thermally cured,
wherein when the thermosetting resin film before curing is heated at a raising temperature speed of 10°C/min and then a set temperature of a temperature control system is maintained at 130°C, a time during which a viscosity at a shear rate of 1 s⁻¹ is equal to or lower than 100,000 Pa·s is equal to or longer than 500 seconds.
2. A first protective film forming sheet comprising the thermosetting resin film according to Claim 1 on one surface of a first supporting sheet.
3. A method for forming a first protective film, comprising:
forming the first protective film by thermally curing the thermosetting resin film according to Claim 1 while pressurizing at a pressure of equal to or greater than 0.1 Pa.